

# QVxx12xHx Series

## 12 A High-Temperature Alternistor TRIACs

HF RoHS

### Description

This 12 A high-temperature Alternistor TRIAC, offered in TO-220AB, TO-220 isolated, TO-251, TO-252, and TO-263 packages, has rated 150 °C maximum junction temperature,  $T_{vj(max)}$  and 153 A non-repetitive surge peak on-state current,  $I_{TSM}$  at 60 Hz.

This series enables easier thermal management and increases surge handling capability in AC power control applications such as heater control, motor speed control, and lighting controls.

This QV series TRIAC operates in quadrants I, II, and III, and offers high performance in applications requiring high commutation capability without a snubber circuit.

### Features

- Blocking voltage up to 800 V
- Mechanically and thermally robust clip-attach assembly
- Internally-isolated TO-220 package
- Maximum virtual junction temperature  $T_{vj(max)}$  of 150 °C
- Halogen-free and RoHS-compliant
- UL 1557 recognized as an Electrically Isolated Semiconductor Device (L package: file number E71639)

### Benefits

- High dv/dt up to 1000 V/μs for improved noise immunity
- 3Q technology for high commutation capability, resulting in smoother switching transitions and reduced EMI
- Internally isolated TRIAC packages offer improved thermal management and high electrical isolation, simplifying mounting and enhancing safety.

### Applications

TRIAC is an excellent AC switch in heating, lighting, and motor speed control applications.

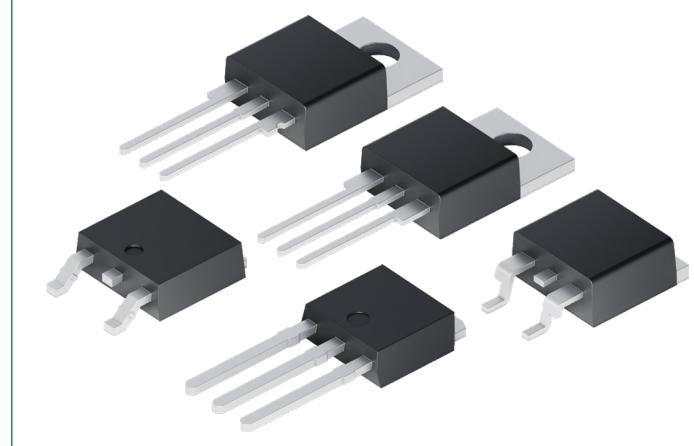
Typical applications are:

- Heater control such as coffee brewer, tankless water heater, and infrared heater
- AC solid-state relays

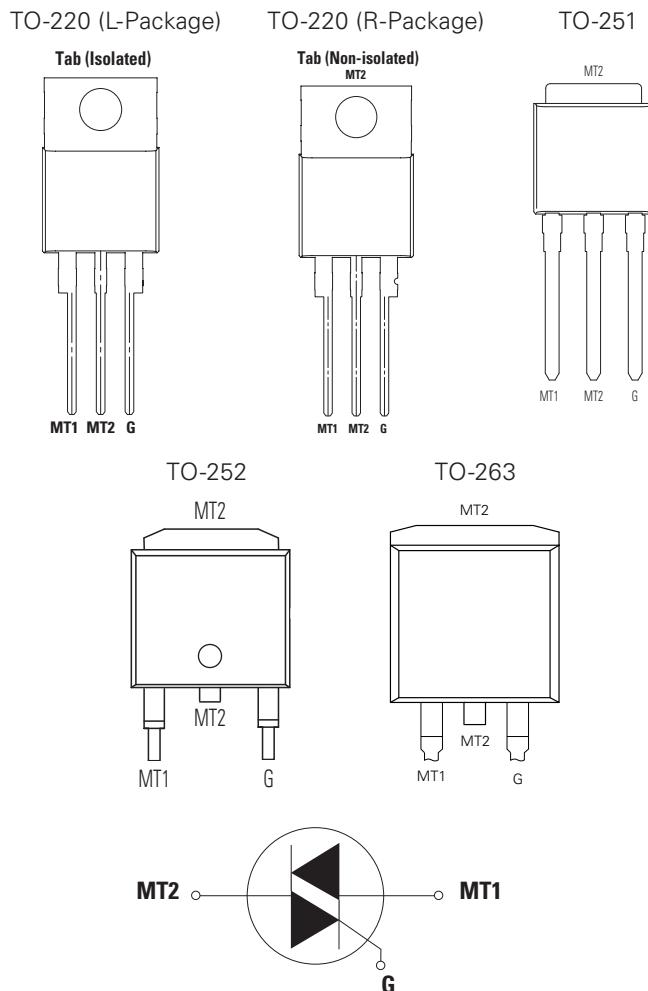
- Light dimmers including incandescent and LED lighting
- Motor speed control in kitchen appliances, white goods, home electronics, power tools, and light industrial applications such as compressor motor control

### Product Summary

Characteristic	Value	Unit
$I_{T(RMS)}$	12	A
$V_{DRM}/V_{RRM}$	600 or 800	V
$I_{GT(Q1)}$	20, 35, or 50	mA



### Pinout Diagram



**MT1:** Main Terminal 1; **MT2:** Main Terminal 2; **G:** Gate

**Maximum Ratings — Alternistor TRIAC** (3 Quadrants)

Symbol	Characteristics	Conditions						Value	Units			
$V_{DSM}/V_{RSM}$	Non-repetitive Surge Peak Off-state Voltage	QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub> / QVxx12LH <sub>y</sub>		$V_{DRM}/V_{RRM} = 600 \text{ V}$		$P_W = 100 \mu\text{s}$	$V_{DRM}/V_{RRM} + 100$		V			
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>		$T_{vj} = 25^\circ\text{C}$			960					
$I_{T(RMS)}$	On-state RMS Current (Full Sine Wave)	QVxx12LH <sub>y</sub>				$T_C = 120^\circ\text{C}$		12	A			
		QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub>				$T_C = 135^\circ\text{C}$						
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>				$T_C = 130^\circ\text{C}$						
$I_{TSM}$	Non-repetitive Surge Peak On-state Current	QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub> / QVxx12LH <sub>y</sub>		$f = 50 \text{ Hz}, t = 20 \text{ ms}$		full cycle; $T_{vj}$ initial = 25 °C	140		A			
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>		$f = 60 \text{ Hz}, t = 16.7 \text{ ms}$			153					
		QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub>		$f = 50 \text{ Hz}, t = 20 \text{ ms}$			105					
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>		$f = 60 \text{ Hz}, t = 16.7 \text{ ms}$			125					
$I^2t$	$I^2t$ Value for Fusing	QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub> / QVxx12LH <sub>y</sub>				$t_p = 8.3 \mu\text{s}$	97		$\text{A}^2\text{s}$			
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>					64					
di/dt	Critical Rate of Rise of On-state Current	$I_G = 50 \text{ mA}$ with $0.1 \mu\text{s}$ rise time		$f = 60 \text{ Hz}, T_{vj} = 150^\circ\text{C}$				100	A/ $\mu\text{s}$			
$I_{GT}$	Peak Gate Trigger Current	QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub> / QVxx12LH <sub>y</sub>		$t_p \leq 10 \mu\text{s}; I_{GT} \leq I_{GTM}, T_{vj} = 150^\circ\text{C}$				4	A			
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>					2					
$P_{G(AV)}$	Average Gate Power Dissipation	QVxx12RH <sub>y</sub> / QVxx12NH <sub>y</sub> / QVxx12LH <sub>y</sub>		$T_{vj} = 150^\circ\text{C}$				0.5	W			
		QVxx12DH <sub>y</sub> / QVxx12VH <sub>y</sub>					0.1					
$T_{stg}$	Storage Temperature Range	—						-40 to 150	°C			
$T_{vj}$	Virtual Junction Temperature Range	—						-40 to 150	°C			

xx = voltage/10; y = sensitivity

**Electrical Characteristics** ( $T_{vj} = 25^\circ\text{C}$ , unless otherwise specified) — **Alternistor TRIAC** (3 Quadrants)

Symbol	Characteristics	Conditions	QVxx12xH3			QVxx12xH4			QVxx12xH5			Units
			Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
$I_{GT}$	DC Gate Trigger Current	$V_D = 12 \text{ V}, R_L = 60 \Omega$	I - II - III	-	-	20	-	-	35	-	-	50 mA
				-	-	1.3	-	-	1.2	-	-	1.2 V
$V_{GD}$	Gate Non-trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega, T_{vj} = 150^\circ\text{C}$	I - II - III	0.2	-	0.15	-	-	0.15	-	-	V
$I_H$	Holding Current	$I_T = 100 \text{ mA}$ Initial		-	-	30	-	-	50	-	-	60 mA
$I_L$	Latching Current	$V_D = 12 \text{ V}; I_G = 24 \text{ mA}$		-	-	80	-	-	-	-	-	mA
$dv/dt$	Critical Rate-of-rise of Off-stage Voltage	$V_D = V_{DRM}$ , Gate Open, $T_{vj} = 150^\circ\text{C}$		-	-	500	-	-	750	-	-	V/ $\mu\text{s}$
		$V_D = 2/3 V_{DRM}$ , Gate Open, $T_{vj} = 150^\circ\text{C}$		1000	-	1000	-	-	1000	-	-	
( $dv/dt$ )c	Critical Rate-of-rise of Commutation Voltage	$T_{vj} = 150^\circ\text{C}, (dv/dt)c = 8.6 \text{ A/ms}$		25	-	50	-	-	50	-	-	V/ $\mu\text{s}$
$t_{gt}$	Turn-on Time	$I_G = 2 \times I_{GT}, P_W = 15 \mu\text{s}, I_T = 22.6 \text{ A}_{pk}$	I	-	1	-	-	1	-	-	1	-
			II	-	1.3	-	-	2	-	-	2	-
			III	-	3	-	-	7	-	-	10	-

xx = voltage/10; y = sensitivity

## Thermal Characteristics

Symbol	Characteristics	Value	Units
$R_{th(j-c)}$	Thermal Resistance, Junction to Case	QVxx12RHy/ QVxx12NHy	0.9
		QVxx12LHy	1.85
		QVxx12DHy/ QVxx12VHy	1.4
$R_{th(j-a)}$	Thermal Resistance, Junction to A(j-a)mbient	QVxx12DHy/ QVxx12VHy	70

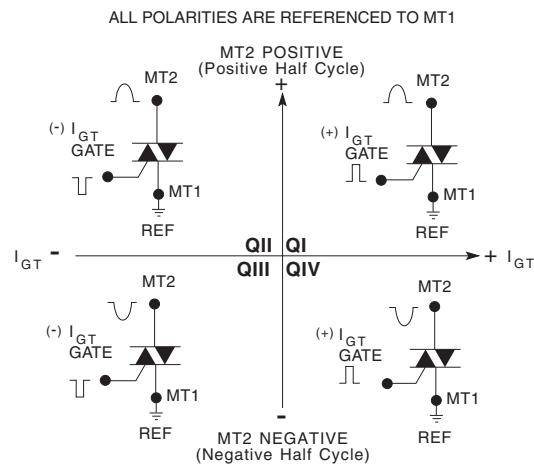
xx = voltage/10; y = sensitivity

## Static Characteristics

Symbol	Characteristics	Conditions	Value			Units
			Min.	Typ.	Max.	
$V_{TM}$	Peak On-state Voltage	$I_T = 17 \text{ A}$ $t_p = 380 \mu\text{s}$	-	-	1.6	V
$I_{DRM}/I_{RRM}$	Off-state Current, Peak Repetitive	$V_D = V_{DRM}/V_{RRM}$ , $T_{vj} = 25^\circ\text{C}$	-	-	5	$\mu\text{A}$
		$V_D = V_{DRM}/V_{RRM}$ , $T_{vj} = 150^\circ\text{C}$	-	-	3	mA
$V_{T0}$	Threshold Voltage	$T_{vj} = 150^\circ\text{C}$	-	-	0.85	V
$R_D$	Slope Resistance	$T_{vj} = 150^\circ\text{C}$	600 V	-	23	$\text{m}\Omega$
			800 V	-	38	

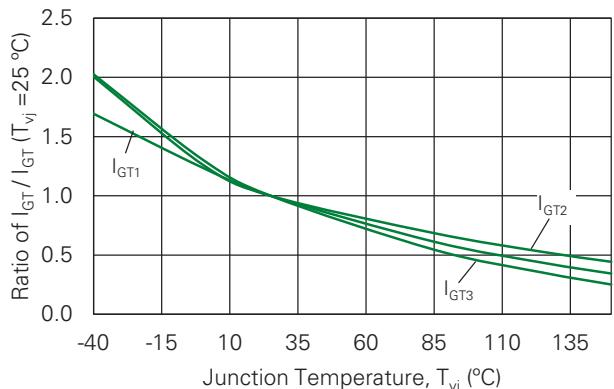
## Characteristic Curves

**Figure 1. Definition of Quadrants**

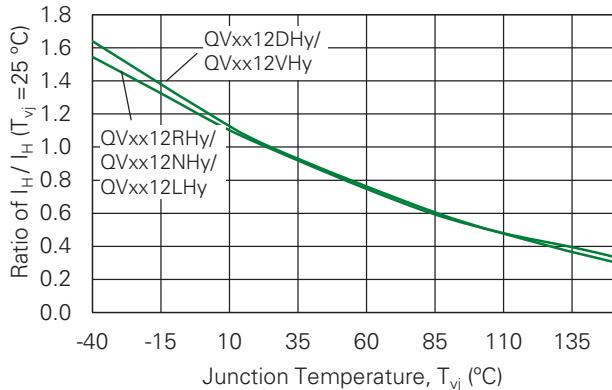


Note: Alternistors will not operate in QIV

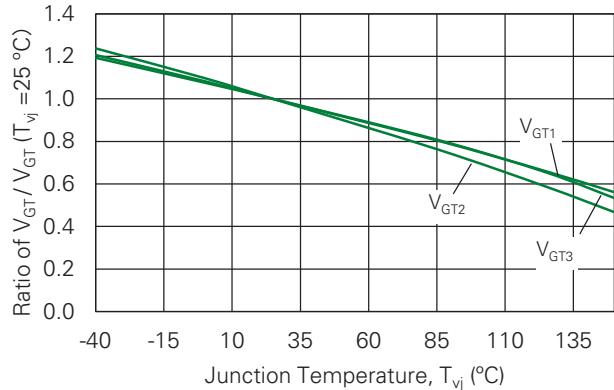
**Fig. 2. Normalized DC Gate Trigger Current for all Quadrants vs. Junction Temperature**



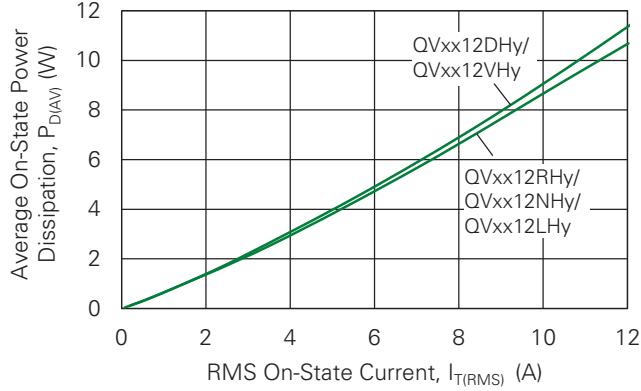
**Fig. 3. Normalized DC Holding Current vs. Junction Temperature**



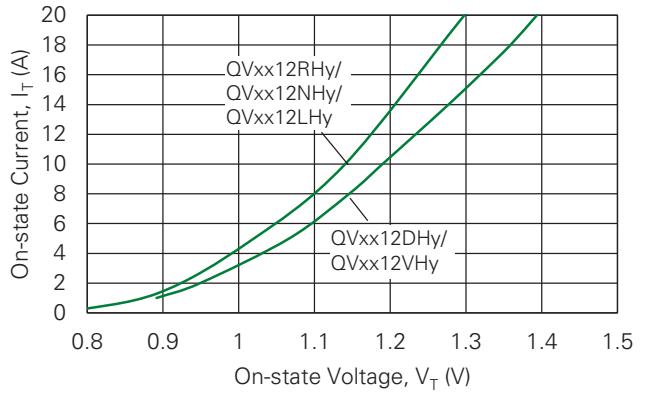
**Fig. 4. Normalized DC Gate Trigger Voltage for all Quadrants vs. Junction Temperature**

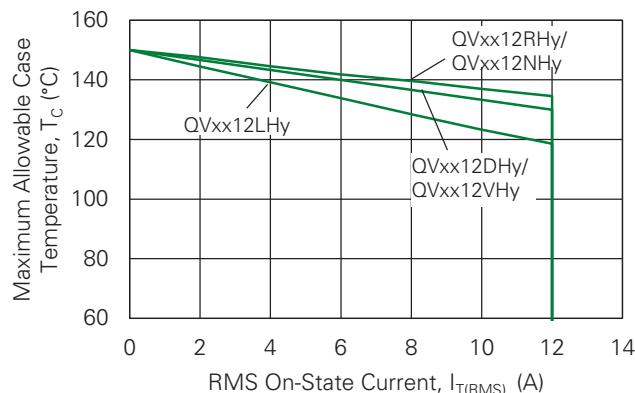
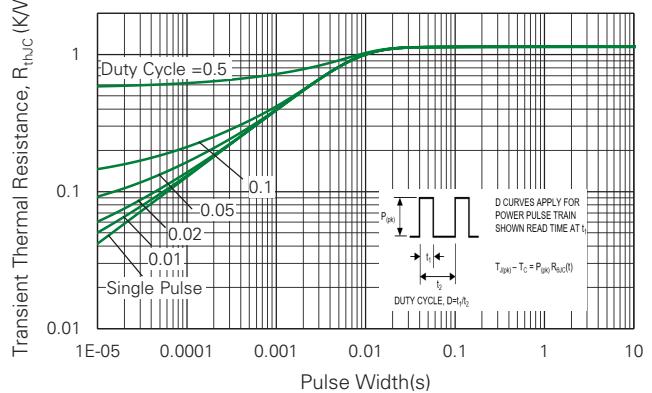
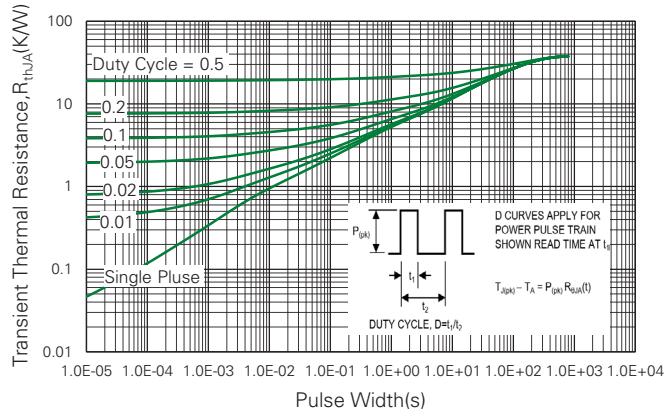
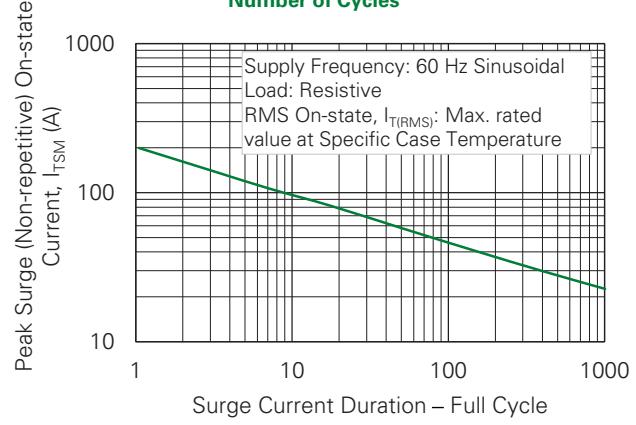


**Fig. 5. Typical Power Dissipation vs. RMS On-state Current**



**Fig. 6. Typical On-state Current vs. On-state Voltage**



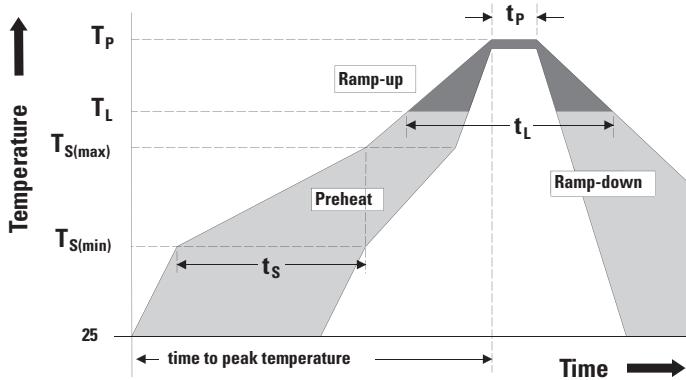
**Fig. 7. Maximum Allowable Case Temperature vs. RMS On-state Current****Figure 8. Junction to Case Transient Thermal Impedance (only for QVxx12DHy/QVxx12VHy)****Figure 9. Junction to Ambient Transient Thermal Impedance (only for QVxx12DHy/QVxx12VHy)****Fig. 10. Surge Peak On-state Current vs. Number of Cycles**

## Notes:

1. Gate control may be lost during and immediately following surge current interval.
2. Overload should not be repeated until junction temperature has returned to steady-state rated value.

## Soldering Parameters

Characteristic		Value
Reflow Condition		Pb – Free assembly
Pre-heat	Temperature Min ( $T_{s(\min)}$ )	150°C
	Temperature Max ( $T_{s(\max)}$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 120 secs
Average ramp up rate (Liquidus Temp) ( $T_L$ ) to peak		3°C/second max
$T_{s(\max)}$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )		260 <sup>+0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		30 seconds max.
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature ( $T_p$ )		6 minutes max
Do Not Exceed		260°C



## Environmental Specifications

Test	Specifications and Conditions
AC Blocking	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 150°C for 1008 hours
Temperature/Humidity	EIA / JEDEC, JESD22-A101, 1008 hours; 160 V - DC: 85°C; 85% relative humidity
Temperature Cycling	MIL-STD-750, M-1051, 1000 cycles; -55°C to +150°C; 15-min dwell-time
UHAST	JESD22A-118, 96 hrs, 130°C/ 85% RH
IOL	MIL-STD-750 Method 1037
Resistance to Solder Heat	MIL-STD-750: Method 2031
Solderability	ANSI/J-STD-002: category 3, Test A
Lead Bend	MIL-STD-750, M-2036 Cond E
Moisture Sensitivity Level	Level 1, JEDEC-J-STD-020

## Physical Specifications

Characteristic	Value
Terminal Finish	100% Matte Tin-plated
Body Material	UL Recognized compound meeting flammability rating 94 V-0
Terminal Material	Copper Alloy

## Product Selector

Part Number	Voltage		Gate Sensitivity Quadrants	Type	Package
	600 V	800 V			
QVxx12DH3	–	X	20 mA	Alternistor TRIAC	TO-252 (DPAK)
QVxx12VH3	–	X	20 mA	Alternistor TRIAC	TO-251 (VPAK)
QVxx12LH4	X	–	35 mA	Alternistor TRIAC	TO-220AB (L package)
QVxx12RH4	X	–	35 mA	Alternistor TRIAC	TO-220AB (R package)
QVxx12NH4	X	–	35 mA	Alternistor TRIAC	TO-263 (D <sup>2</sup> PAK)
QVxx12LH5	X	–	50 mA	Alternistor TRIAC	TO-220AB (L package)
QVxx12RH5	X	–	50 mA	Alternistor TRIAC	TO-220AB (R package)
QVxx12NH5	X	–	50 mA	Alternistor TRIAC	TO-263 (D <sup>2</sup> PAK)

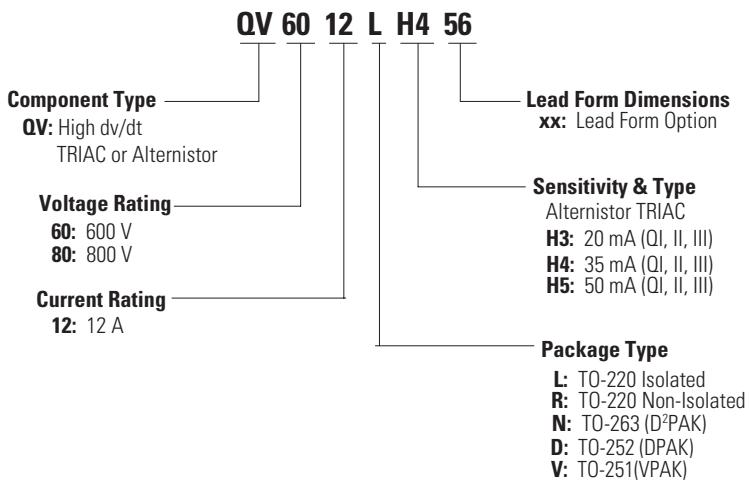
xx = voltage/10; y = sensitivity

## Packing Options

Part Number	Marking	Weight	Packing Mode	Base Quantity
QVxx12LHyTP	QVxx12LHy	2.2 g	Tube Pack	1000
QVxx12RHyTP	QVxx12RHy	2.2 g	Tube Pack	1000
QVxx12NHyTP	QVxx12NHy	1.6 g	Tube Pack	1000
QVxx12NHyRP	QVxx12NHy	1.6 g	Embossed Carrier	500
QVxx12DHyTP	QVxx12DHy	0.3 g	Tube Pack	750 (75 per tube)
QVxx12DHyRP	QVxx12DHy	0.3 g	Embossed Carrier	2500
QVxx12VHyTP	QVxx12VHy	0.4 g	Tube Pack	750 (75 per tube)

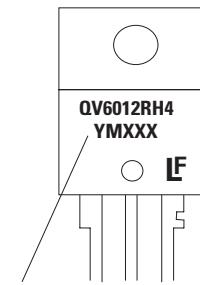
xx = voltage/10; y = sensitivity

## Part Numbering and Marking



**TO-220 AB - (L and R Package)**

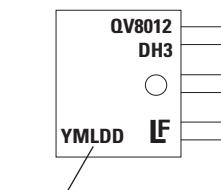
**TO-263 - (N Package)**



**Date Code Marking**

Y: Year Code

**TO-252 (DPAK)**  
**TO-251 (VPAK)**



**Date Code Marking**

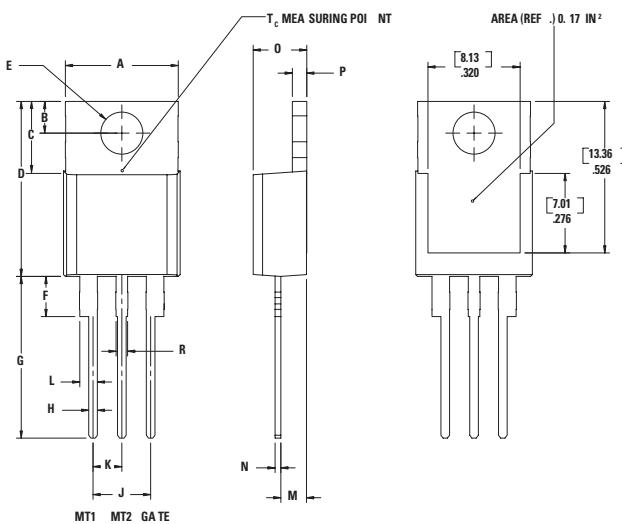
Y: Year Code

M: Month Code

L: Location Code

DD: CalendarCode

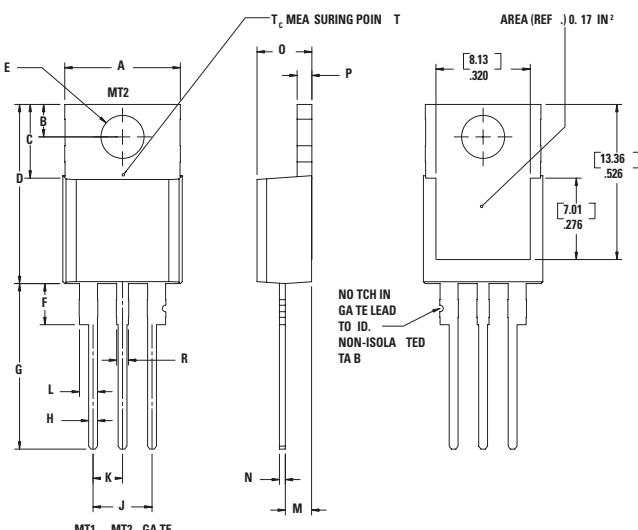
## Package Dimensions TO-220AB (L-Package) – Isolated Mounting Tab



**Note:** Maximum torque to be applied to mounting tab is 8 in-lbs. (0.904 Nm).

Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	9.65	10.67	0.380	0.420
B	2.67	2.92	0.105	0.115
C	5.84	6.35	0.230	0.250
D	14.99	15.75	0.590	0.620
E	3.61	3.73	0.142	0.147
F	2.79	3.30	0.110	0.130
G	13.72	14.60	0.540	0.575
H	0.64	0.89	0.025	0.035
J	4.95	5.21	0.195	0.205
K	2.41	2.67	0.095	0.105
L	1.52	1.91	0.060	0.075
M	2.16	2.41	0.085	0.095
N	0.46	0.61	0.018	0.024
O	4.52	4.78	0.178	0.188
P	1.14	1.52	0.045	0.060
R	0.97	1.22	0.038	0.048

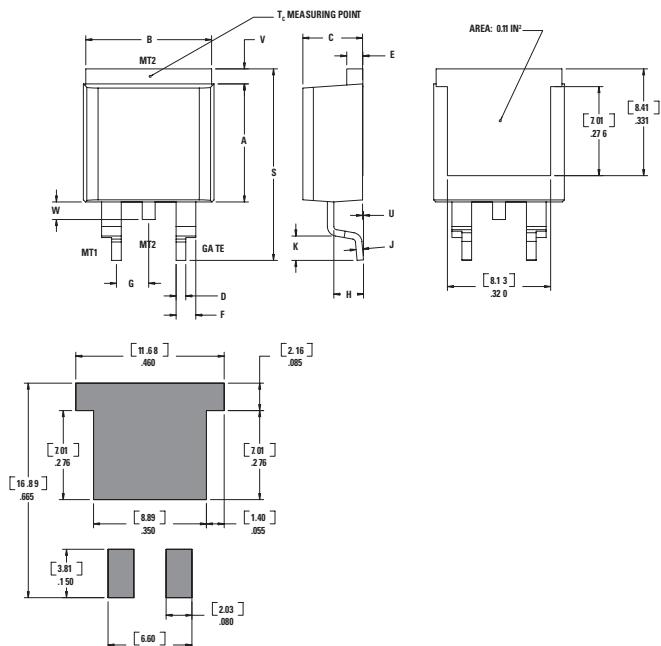
## Package Dimensions TO-220AB (R Package) – Non-isolated Mounting Tab Common with Center Lead



**Note:** Maximum torque to be applied to mounting tab is 8 in-lbs. (0.904 Nm).

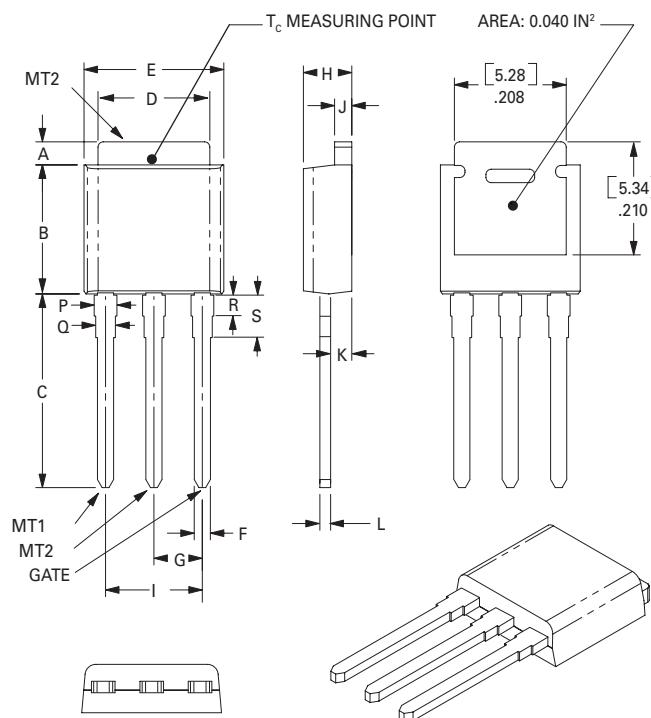
Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	9.65	10.67	0.380	0.420
B	2.67	2.92	0.105	0.115
C	5.84	6.35	0.230	0.250
D	14.99	15.75	0.590	0.620
E	3.61	3.73	0.142	0.147
F	2.79	3.30	0.110	0.130
G	13.72	14.60	0.540	0.575
H	0.64	0.89	0.025	0.035
J	4.95	5.21	0.195	0.205
K	2.41	2.67	0.095	0.105
L	1.52	1.91	0.060	0.075
M	2.16	2.41	0.085	0.095
N	0.46	0.61	0.018	0.024
O	4.52	4.78	0.178	0.188
P	1.14	1.52	0.045	0.060
R	0.97	1.22	0.038	0.048

## Package Dimensions TO-263 (N Package) – D<sup>2</sup>PAK Surface Mount



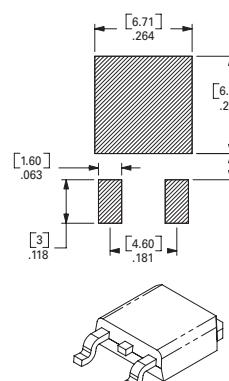
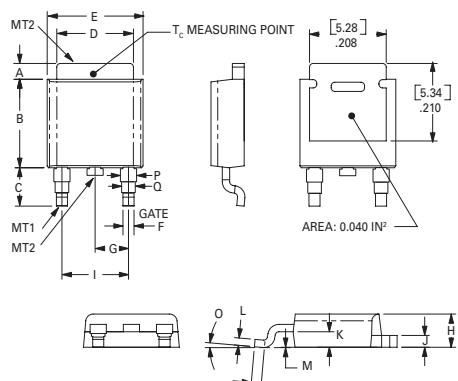
Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	9.14	9.40	0.360	0.370
B	9.65	10.67	0.380	0.420
C	4.52	4.78	0.178	0.188
D	0.64	0.89	0.025	0.035
E	1.14	1.52	0.045	0.060
F	1.52	1.91	0.060	0.075
G	2.41	2.67	0.095	0.105
H	2.34	2.59	0.092	0.102
J	0.46	0.61	0.018	0.024
K	2.29	2.79	0.090	0.110
S	14.99	15.88	0.590	0.625
V	0.89	1.14	0.035	0.045
U	0.05	0.25	0.002	0.010
W	1.02	1.78	0.040	0.070

## Package Dimensions TO-251AA (V Package) – VPAK Through Hole



Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.94	1.09	0.037	0.043
B	5.97	6.22	0.235	0.245
C	8.89	9.53	0.350	0.375
D	5.21	5.41	0.205	0.213
E	6.48	6.73	0.255	0.265
F	0.69	0.84	0.027	0.033
G	2.21	2.36	0.087	0.093
H	2.16	2.41	0.085	0.095
I	4.47	4.67	0.176	0.184
J	0.46	0.58	0.018	0.023
K	0.90	1.00	0.035	0.039
L	0.46	0.58	0.018	0.023
P	1.06	1.32	0.042	0.052
Q	0.86	1.11	0.034	0.044
R	0.86	1.11	0.034	0.044
S	1.86	2.11	0.074	0.084

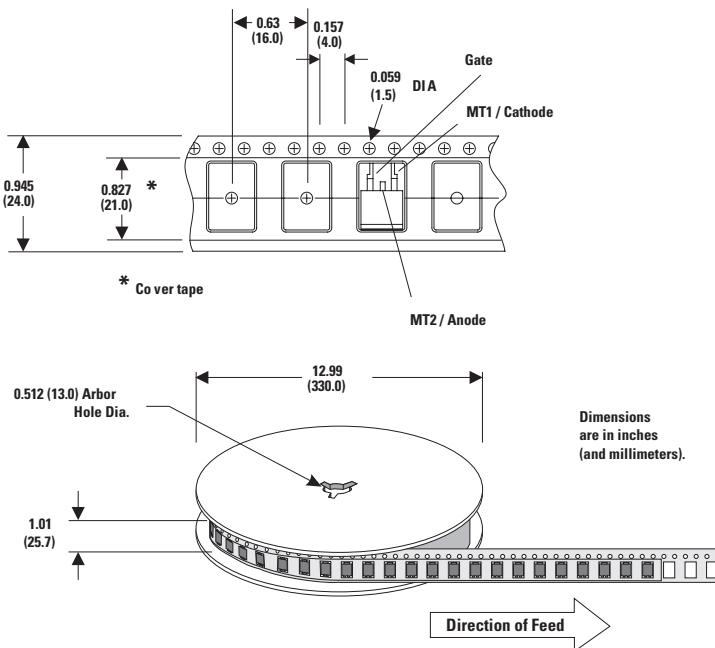
## Package Dimensions TO-252AA (D Package) – DPAK Surface Mount



Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.94	1.09	0.037	0.043
B	5.97	6.22	0.235	0.245
C	2.69	2.87	0.106	0.113
D	5.21	5.41	0.205	0.213
E	6.48	6.73	0.255	0.265
F	0.69	0.84	0.027	0.033
G	2.21	2.36	0.087	0.093
H	2.16	2.41	0.085	0.095
I	4.47	4.67	0.176	0.184
J	0.46	0.58	0.018	0.023
K	0.90	1.00	0.035	0.039
L	0.46	0.58	0.018	0.023
M	0.00	0.10	0.000	0.004
N	0.53	0.69	0.021	0.027
O	0°	5°	0°	5°
P	1.06	1.32	0.042	0.052
Q	0.86	1.11	0.034	0.039

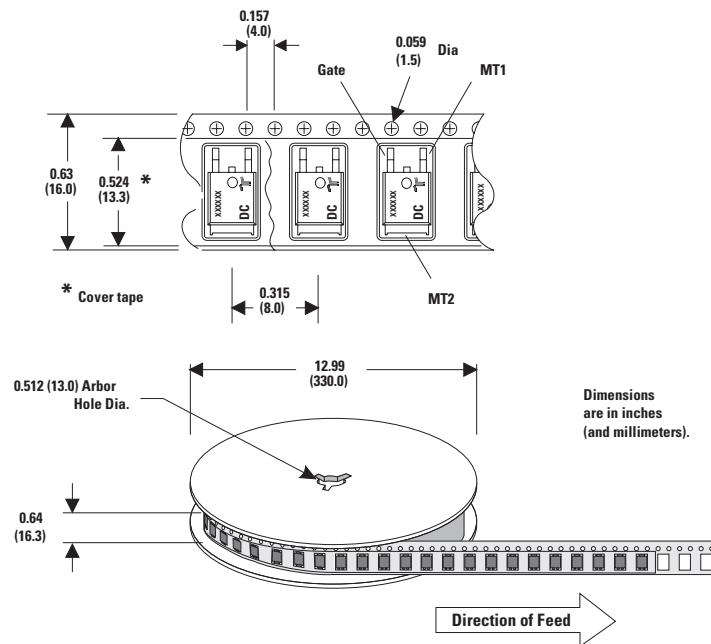
## Reel Pack (RP) Specifications (TO-263 Embossed Carrier)

Meets all EIA-481-2 Standards



**Reel Pack (RP) Specifications (TO-252 Embossed Carrier)**

Meets all EIA-481-2 Standards

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